

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: <i>Evan G Colgan, et al.</i>	Date: <i>October 11, 2006</i>
Serial Number: <i>10/711,023</i>	Examiner: <i>Victor A Mandala</i>
	Confirmation No. <i>5022</i>
Filed: <i>August 18, 2004</i>	Group Art Unit: <i>2826</i>
Title: <i>MULTIPLE POWER DENSITY CHIP STRUCTURE</i>	IBM Corporation D/18G, B/300, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

AMENDMENT AFTER FINAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated August 11, 2006, the following
Amendment is being submitted to place the above identified application in *prima
facie* condition for allowance. Please amend the application as follows: